



(12) **CORRECTED EUROPEAN PATENT APPLICATION**
published in accordance with Art. 153(4) EPC

(15) Correction information:
Corrected version no 1 (W1 A1)
Corrections, see
Bibliography INID code(s) 71

(51) International Patent Classification (IPC):
G01R 1/067 ^(2006.01) **G01R 1/04** ^(2006.01)
G01R 31/28 ^(2006.01)

(48) Corrigendum issued on:
14.12.2022 Bulletin 2022/50

(52) Cooperative Patent Classification (CPC):
G01R 1/0466; G01R 1/06722; G01R 1/06738;
G01R 1/07314; G01R 31/2863

(43) Date of publication:
17.08.2022 Bulletin 2022/33

(86) International application number:
PCT/KR2019/017865

(21) Application number: **19948172.2**

(87) International publication number:
WO 2021/066255 (08.04.2021 Gazette 2021/14)

(22) Date of filing: **17.12.2019**

(84) Designated Contracting States:
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB
GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO
PL PT RO RS SE SI SK SM TR
Designated Extension States:
BA ME
Designated Validation States:
KH MA MD TN

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(30) Priority: **02.10.2019 KR 20190122622**

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(54) **SPRING CONTACT AND TEST SOCKET HAVING SPRING CONTACT EMBEDDED THEREIN**

(57) A test socket of the present invention comprises: a plurality of spring contacts, each of which includes an upper contact pin, a lower contact pin, and a coil spring for elastically supporting the upper contact pin and the lower contact pin; a main plate including a plurality of receiving holes formed to allow the spring contacts to be received and positioned therein, respectively, and including first openings, each of which is formed to have a diameter (d2) smaller than the diameter (d1) of the receiving hole so as to support the upper contact pin; and a film plate disposed under the main plate and including second openings, each of which is formed at a position corresponding to the receiving hole, and has a diameter (d3) smaller than the diameter (d1) of the receiving hole so as to support the lower contact pin (120).

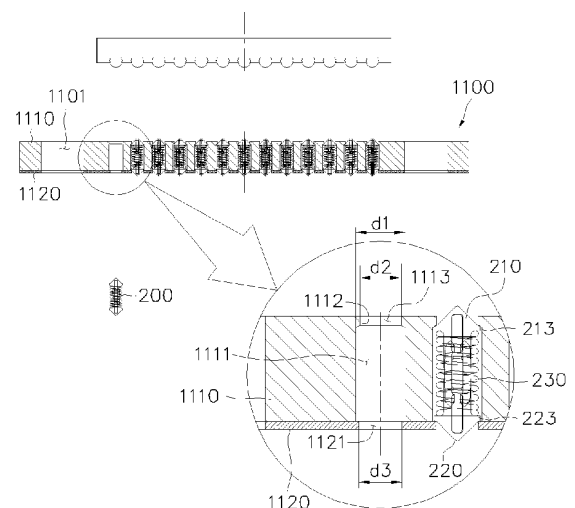


FIG. 22